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Innovativity To Productivity

PRODUCTIVE TECHNOLOGIES COMPANY LIMITED

普達特科技有限公司*

(Incorporated in Bermuda and continued in the Cayman Islands with limited liability)

(Stock Code: 650)

UPDATE ON DEVELOPMENT OF EQUIPMENT FOR SEMICONDUCTOR

This announcement is made by Productive Technologies Company Limited (the "**Company**") on a voluntary basis to keep the shareholders and potential investors of the Company informed of the latest business development of the Company.

Reference is made to the announcement of the Company dated February 11, 2026 in relation to the development of the equipment for semiconductor (the "**Announcement**"). Unless the context requires otherwise, the capitalized terms contained herein will have the same meanings as those defined in the Announcement.

SEMICONDUCTOR LPCVD FURNACE TUBE EQUIPMENT AND CLEANING EQUIPMENT HAVE PASSED CUSTOMER ACCEPTANCE TESTS

A 12-inch LPCVD furnace tube equipment produced by the Company which is used for LP-SiN thin film deposition processes has successfully passed customer acceptance tests. In addition, another one, a 12-inch ALD furnace tube equipment, which is used for ALD-SiN/ALD-SiCN thin film deposition processes and is compatible with both Thermal and Plasma modes, is currently undergoing validation at the customer site.

The advanced semiconductor furnace tube equipment product line of the Company comprises two major equipment platforms, namely Galilee-LP and Galilee-ALD, dedicated to serving the 12-inch logic process, DRAM and 3D NAND sectors, whose applications cover critical thin film deposition processes for advanced technology nodes from 65nm to 7nm and which are capable of depositing a wide range of film materials such as SiN, Poly and TEOS. The market of such equipment is predominantly dominated by overseas suppliers, with an extremely low localization rate in China. Those types of equipments produced by the Company achieve higher aspect ratio filling, uniformity, step coverage rate and lower contamination levels, meeting international standards in advanced performance metrics, while offering higher batch productivity and compatibility with multiple process options. Notably, in the area of advanced application development, the Company has completed development of a Low-K ALD SiOCN furnace tube equipment for 14/7nm nodes, designed to meet the demand for high-performance insulating layers in large-scale integrated circuits, and currently, this equipment sector remains dominated by overseas equipment manufacturers.

In addition, the semiconductor single-wafer cleaning equipment produced by the Company continues to expand its customer base and accumulate mass production experience. Since October 2025 and up to now, we have five units of 6- to 12-inch CUBE single-wafer cleaning equipment that have successfully passed acceptance tests at multiple high-quality customers and are applied in areas such as SiC/power devices/mixed-signal chips, among which two units represent repeat orders. Designed for backside cleaning and etching processes, this equipment features ultra-thin wafer handling capabilities, industry-leading Bernoulli transport and wafer edge control technologies, and delivers industry-leading productivity to customers through architectural innovation. To the best of the Board's knowledge, information and belief, having made all reasonable enquiries, the customers mentioned above and their ultimate beneficial owners are third parties independent of the Company and its connected persons as at the date of this announcement.

Going forward, the Company will continue to complete the delivery and acceptance of its advanced semiconductor furnace tube equipment and cleaning equipment, further expand its high-quality customer base, and fully leverage its technological advantages to drive further breakthroughs in the domestic substitution of advanced semiconductor equipment.

GENERAL

The transactions contemplated under the equipment delivery do not constitute notifiable transactions of the Company under Chapter 14 of the Rules Governing the Listing of Securities on The Stock Exchange of Hong Kong Limited. The Company will make further announcement(s) as and when appropriate if required.

Shareholders and potential investors are advised to exercise caution when dealing in the securities of the Company.

By Order of the Board
Productive Technologies Company Limited
Liu Erzhuang
Chairman and Chief Executive Officer

Hong Kong, March 24, 2026

As at the date hereof, the Board comprises eight Directors, of whom three are executive Directors, namely Dr. Liu Erzhuang (Chairman), Mr. Tan Jue and Mr. Liu Zhihai; two are non-executive Directors, namely Mr. Cao Xiaohui and Mr. Lin Yukai; and three are independent non-executive Directors, namely Ms. Ge Aiji, Mr. Chau Shing Yim David, and Mr. Wang Guoping.

* *For identification purposes only*